

LTM4606- PBF-BGA -133LD 15mm X 15mm X 3.42mm (TABLE OF MATERIAL DECLARATION)							
The LTM4606 is RoHS compliant per EU RoHS Directive 2003/95/EC.							
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)							
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2189	Barium Compounds	7727-43-7	0.00589	2.69
				Bismaleimide/Triazine Resin/Filler substances(Silice crystalline)	105391-33-1,1156-51-0/9003-36-5/2,1645-51-2 non discolorure	0.05882	26.87
				Copper Metal	7440-50-8	0.08839	40.38
				Copper Compounds	147-14-8	0.00005	0.02
				Ecotoxic substances	7440-38-2	0.00000	0.00
				Ecotoxic substances	7440-28-0	0.00000	0.00
				Gold metal or alloy	7440-57-5	0.00081	0.37
				Nickel	7440-02-0	0.00528	2.41
				Zinc	7440-66-6	0.00005	0.02
				Continuous Filament Fiber Glass	65997-17-3	0.04621	21.11
				Acrylic Resin	non-disclosure	0.01119	5.11
				Epoxy Resin	non-disclosure	0.00018	0.08
				Chromium(III) Oxide	1308-38-9	0.00000	0.00
				Silica amorphous	7631-86-9	0.00031	0.14
				Talc;not containing fibers like asbestos	14807-96-6	0.00068	0.31
				Aromatic Carbonyl compounds	non-disclosure	0.00063	0.29
				Cyanoguanidine	461-58-5	0.00002	0.01
				Calcium caobonate	471-34-1	0.00003	0.02
				Amine compounds	non-disclosure	0.00009	0.04
				Leveling agent and others	non-disclosure	0.00026	0.12
2	Solder Paste	Alloy	0.0161	Sn	7440-31-5	0.01529	95.00
				Sb	7440-36-0	0.00080	5.00
3	Passive/Active Components		0.5719	Iron Powder (Fe)	7439-89-6	0.36347	63.55
				Copper (Cu)	7440-50-8	0.12379	21.65
				Nickel (Ni)	7440-02-0	0.01003	1.75
				Tin (Sn)	7440-31-5	0.00565	0.99
				Ceramic (Ba) Compounds	12047-27-7	0.06895	12.06
4	Active Ics	Silicon	0.0100	Silicon	7440-21-3	0.01004	100.00
5	Wire	Gold	0.0024	Au	7440-57-5	0.00244	99.99
6	Encapsulation	Epoxy Resin	0.9238	Fused Silica	60676-86-0	0.71320	77.20
				Epoxy Resin	non-disclosure	0.08222	8.90
				Phenol Resin	non-disclosure	0.08222	8.90
				Crytalline Silica	14808-60-7	0.02771	3.00
				Carbon Black	1333-86-4	0.00462	0.50
				Metal Hydroxide	non-disclosure	0.01386	1.50
9	Solder Ball	Alloy	0.2527	Tin (Sn)	7440-31-5	0.24386	96.50
				Silver (Ag)	7440-22-4	0.00758	3.00
				Copper (Cu)	7440-50-8	0.00126	0.50
Total Package Weight			1.9958				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts